捷多邦,专业PCB打样工厂,24小**74ALVG**HS162830A 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS

DBB PACKAGE

(TOP VIEW)

SCES624 - FEBRUARY 2005

- Member of the Texas Instruments
 Widebus™ Family
- Output Ports Have Series Damping Resistors, So No External Resistors Are Required
- Diodes on Inputs Clamp Overshoot
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

This 1-bit to 2-bit address driver is designed for 2.3-V to 3.6-V V_{CC} operation.

Diodes to V_{CC} have been added on the inputs to clamp overshoot.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The outputs, which are designed to sink up to 12 mA, include series damping resistors to reduce overshoot and undershoot.

The ALVCHS162830A is an improved version of the LVCHS162830 (non-A version) and has been optimized for lower power consumption and higher AC drive. Higher AC drive provides capability to drive loads with a faster edge rate.

To ensure the high-impedance state during power up or power down, the output-enable (\overline{OE}) input should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

	1				ı	
2Y2		1	\cup	80		1Y3
1Y2		2		79		2Y3
GND		3		78	þ	GND
2Y1		4		77		1Y4
1Y1		5		76		2Y4
V_{CC}		6		75		V_{CC}
A1		7		74		1Y5
A2		8		73	þ	2Y5
GND		9		72		GND
А3		10		71		1Y6
A4		11		70		2Y6
GND		12		69		GND
A5		13		68		1Y7
A6		14		67		2Y7
VCC		15		66		V_{CC}
A7		16		65		1Y8
A8		17		64		2Y8
GND		18		63		GND
A9		19		62		1Y9
OE1		20		61		2Y9
OE2		21		60		1Y10
A10		22		59		2Y10
GND		23		58		GND
A11		24		57		1Y11
A12		25		56	þ	2Y11
VCC		26		55		V_{CC}
A13		27		54	þ	1Y12
A14		28		53		2Y12
GND		29		52	þ	GND
A15		30		51	þ	1Y13
A16		31		50		2Y13
GND		32		49		GND
A17	Ц	33		48		1Y14
A18		34		47		2Y14
VCC		35		46		VCC
2Y18		36		45		1Y15
1Y18		37		44	0	2Y15
GND		38		43		GND
2Y17		39		42		1Y16
1Y17		40		41		2Y16

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description/ordering information

ORDERING INFORMATION

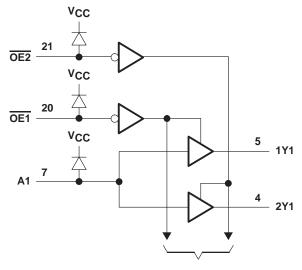
TA	PACKAGEŤ		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TVSOP – DBB	Tape and reel	74ALVCHS162830AGR	ALVCHS162830A

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS	OUTI	PUTS	
OE1	OE2	Α	1Yn	2Yn
L	Н	Н	Н	Z
L	Н	L	L	Z
Н	L	Н	Z	Н
Н	L	L	Z	L
L	L	Н	Н	Н
L	L	L	L	L
Н	Н	Χ	Z	Z

logic diagram (positive logic)



To 17 Other Channels

74ALVCHS162830A 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS SCES624 - FEBRUARY 2005

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} Input voltage range, V_{I} (see Note 1) Output voltage range, V_{O} (see Notes 1 and 2) Input clamp current, I_{IK} (V_{I} < 0, V_{I} > V_{CC}) Output clamp current, I_{OK} (V_{O} < 0) Continuous output current, I_{O} Continuous current through each V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3)	$ \begin{array}{llllllllllllllllllllllllllllllllllll$
Package thermal impedance, θ_{JA} (see Note 3)	64°C/W

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.3	3.6	V
V	High lavel input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
V_{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
1/	Law law line was to selle an	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	VCC	V
		$V_{CC} = 2.3 \text{ V}$		-6	
lOH	High-level output current	$V_{CC} = 2.7 \text{ V}$		-8	mA
		V _{CC} = 3 V		-12	
		$V_{CC} = 2.3 \text{ V}$		6	
lOL	Low-level output current	$V_{CC} = 2.7 \text{ V}$		8	mA
		V _{CC} = 3 V		12	
Δt/Δν	Input transition rise or fall rate			10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



74ALVCHS162830A 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS SCES624 - FEBRUARY 2005

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETE	ER	TEST C	ONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT	
.,		I _I = -18 mA		2.3 V			-1.2		
VIK		I _I = 18 mA		2.3 V		VC	ე + 1.2	V	
		I _{OH} = -100 μA		2.3 V to 3.6 V	Vcc -	0.2			
		$I_{OH} = -4 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.9				
.,			V _{IH} = 1.7 V	2.3 V	1.7			.,	
VOH		$I_{OH} = -6 \text{ mA}$	V _{IH} = 2 V	3 V	2.4			V	
		$I_{OH} = -8 \text{ mA},$	V _{IH} = 2 V	2.7 V	2				
		$I_{OH} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2				
		I _{OL} = 100 μA		2.3 V to 3.6 V			0.2		
		I _{OL} = 4 mA,	V _{IL} = 0.7 V	2.3 V			0.4		
.,			V _{IL} = 0.7 V	2.3 V			0.55	V	
VOL		$I_{OL} = 6 \text{ mA}$	V _{IL} = 0.8 V	3 V			0.55		
		I _{OL} = 8 mA,	V _{IL} = 0.8 V	2.7 V			0.6		
		I _{OL} = 12 mA,	V _{IL} = 0.8 V	3 V			0.8		
II		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
		V _I = 0.7 V		2.3 V	45				
		V _I = 1.7 V		2.3 V	-45				
l _{l(hold)}		V _I = 0.8 V		3 V	75			μΑ	
(/		V _I = 2 V		3 V	-75				
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$		3.6 V			±500		
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μА	
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			20	μА	
ΔlCC		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			500	μА	
Contro	ol inputs			0.01/		3.5			
C _i Data i	inputs	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF	
C _O Outpu	uts	$V_O = V_{CC}$ or GND		3.3 V		4.5		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		FROM	TO	V _{CC} =		VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
		(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
	^t pd	А	Υ	1.2	3.8		4	1.7	3.5	ns
	^t en	ŌĒ	Υ	1	5.7		5.7	1	4.8	ns
	^t dis	ŌĒ	Y	1	4.9		5.4	1.7	5.2	ns

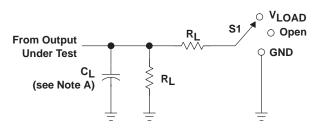
operating characteristics, T_A = 25°C

	PARAMETER			ONDITIONS	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V	UNIT
<u> </u>	Power dissipation capacitance	One OE enabled	C. 0	f = 10 MHz	17	17.5	pF
C _{pd}	per bit (one output switching)	All outputs disabled	$C_L = 0$,	1 = 10 MHZ	0.4	0.5	þг



[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

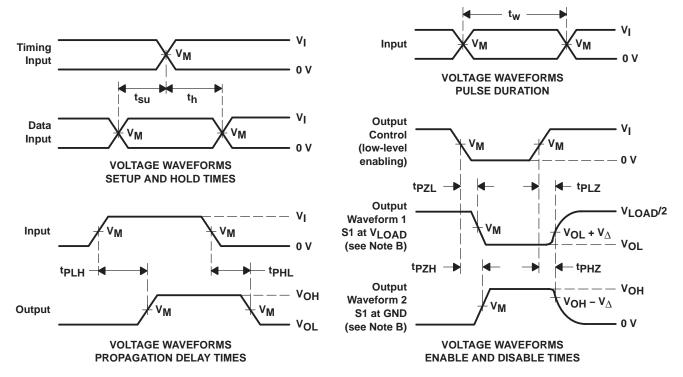
PARAMETER MEASUREMENT INFORMATION



TEST	S1
^t pd	Open
tPLZ/tPZL	V _{LOAD}
tPHZ/tPZH	GND

LOAD CIRCUIT

V	IN	PUT	.,	V	•	Б	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Vcc	٧ı	t _r /t _f	V _M	VLOAD	CL	R_L	$v_{\scriptscriptstyle\Delta}$
2.5 V ± 0.2 V	vcc	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V ± 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

27-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCHS162830AGR	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ALVCHS162830AGRE4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ALVCHS162830AGRG4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

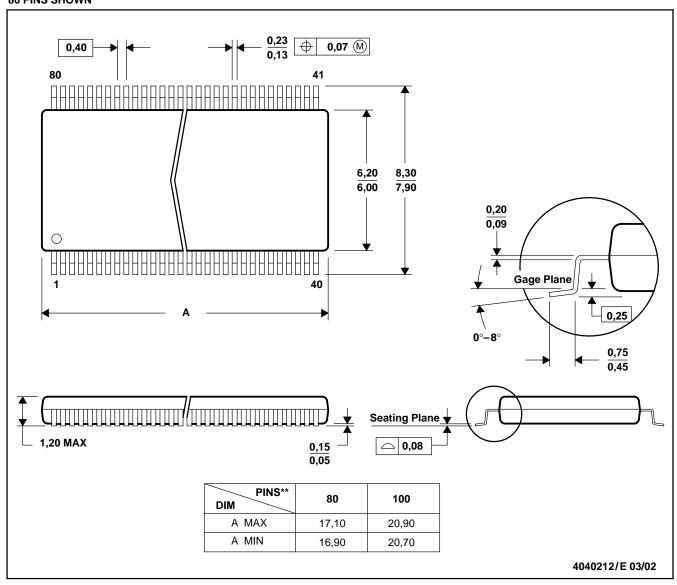
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DBB (R-PDSO-G**)

80 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC: 80 Pin – MO-153 Variation FF

100 Pin - MO-194 Variation BB

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